Title (en)

Exposure method for forming pattern for IC chips on reticle by use of master masks

Title (de)

Belichtungsverfahren zur Erzeugung eines Musters für IC-Chips auf einem Retikel unter Verwendung von Originalmasken

Title (fr)

Méthode d'exposition pour former un motif pour puces de circuits intégrés sur un réticule utilisant des masques originaux

Publication

EP 1249733 A3 20050209 (EN)

Application

EP 02007382 A 20020409

Priority

JP 2001110309 A 20010409

Abstract (en)

[origin: EP1249733A2] There is provided a method which forms master masks used when a pattern of size larger than a region which can be exposed at one time is exposed on a to-be-exposed object (2). The pattern of the size larger than the region which can be exposed at one time is divided into a region (4) of low repetitiveness and a region (A) of high repetitiveness. A pattern of the region (4) of low repetitiveness is drawn on at least one first master mask (1-5, 1-6). Further, a pattern of the region (A) of high repetitiveness is drawn on at least one second master mask (1-1 to 1-4). <IMAGE>

IPC 1-7

G03F 7/20

IPC 8 full level

G03F 1/68 (2012.01); **G03F 1/70** (2012.01); **G03F 1/76** (2012.01); **G03F 7/20** (2006.01); **H01L 21/027** (2006.01)

CPC (source: EP KR US)

G03F 1/00 (2013.01 - EP US); **G03F 1/50** (2013.01 - EP US); **G03F 7/70466** (2013.01 - EP US); **H01L 21/027** (2013.01 - KR)

Citation (search report)
- [XA] US 6165692 A 20001226 - KANAI HIDEKI [JP], et al
- [X] US 5705299 A 19980106 - TEW CLAUDE E [US], et al
- [X] US 5567575 A 19961022 - HIRAMA MASAHIDE [JP]
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Designated contracting state (EPC)

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DOCDB simple family (publication)

EP 1249733 A2 20021016; **EP 1249733 A3 20050209**; CN 1221867 C 20051005; CN 1380584 A 20021120; JP 2002303968 A 20021018; JP 4266079 B2 20090520; KR 100464740 B1 20050106; KR 20020079530 A 20021019; TW 583504 B 20040411; US 2002160277 A1 20021031; US 7029799 B2 20060418

DOCDB simple family (application)

EP 02007382 A 20020409; CN 02106195 A 20020409; JP 2001110309 A 20010409; KR 20020019186 A 20020409; TW 91107090 A 20020409; US 11805002 A 20020409